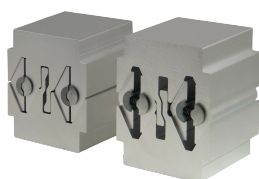


Interscale Flexible Heat Conductor (FHC), 70 mm

Power Utilities



Conductor block expands/contracts vertically to compensate for tolerance stack up and optimizes surface contact and pressure along the thermal path; eliminates the need for a thermal gap pad.

CERTIFICERINGER



FUNKTIONER

Designed for ATX/ITX/Mini ITX & COM using Intel core-ipcprocessors and AMD processors with the following sockets: Intel: LGA775, LGA1150, LGA1155, LGA1156, LGA1366,LGA2011 ; AMD: AM2, AM2(+), AM3, AM3(+), FM1, FM2, FM2(+)

Compatible with Interscale C enclosures

Provides industry leading conduction cooling performance, 70% improvement over current conduction cooling methods

Conductor block expands/contracts vertically to compensate fortolerance stack up and optimizes surface contact and pressurealong the thermal path; eliminates the need for a thermal gappad

Secured to PCB with mounting brackets, sold separately

SPECIFIKATIONER

Table 1/1

Katalognummer	Type	Works With	Pakke mængde	Dybde	Bredde
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24830-001	Heat Conductor	Cases	1	50 mm	50 mm
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YDERLIGERE PRODUKTOPLYSNINGER

Please order the mounting bracket (Intel or AMD, listed under accessories) to assemble the FHC to the board.

ADVARSEL

nVent-produkter skal kun installeres og anvendes som angivet i nVents produktvejledninger og træningsmaterialer. Vejledninger er tilgængelige på www.nvent.com og hos din nVent kundeservicerepræsentant. Forkert installation, misbrug, fejlanvendelse eller anden undladelse af fuldt ud at følge nVents instruktioner og advarsler kan medføre funktionsfejl, materielle skader, alvorlige personskader eller død og/eller ugyldiggøre din garanti.



Vores kraftfulde portefølje af mærker:

CADDY ERICO HOFFMAN ILSCO SCHROFF TRACHTE